

**Amendments to the Claims**

Please amend the claims to read as follows.

1. (Currently Amended): An optical submount comprising:
  - a) a crystalline substrate;
  - b) an anisotropically etched groove in the substrate; and
  - c) a dry pit intersecting the groove at one end of the groove, wherein the dry pit intersects a wedge area of the groove and wherein the dry pit has a triangular shape aligned symmetrically with the groove.
2. (Original) The optical submount of claim 1 wherein the dry pit is deeper than the groove.
3. (Canceled).
4. (Original) The optical submount of claim 1 wherein the dry pit covers a wedge area of the groove.
5. (Original) The optical submount of claim 1 wherein the dry pit is formed before the groove.
6. (Original) The optical submount of claim 1 wherein the dry pit includes an etched area to allow for laser beam expansion.
7. (Original) The optical submount of claim 1 wherein the dry pit includes a slot for optical device.
8. (Original) The optical submount of claim 1 wherein the crystalline substrate is a <100> silicon substrate.
9. (Currently Amended): A micromachined crystalline substrate comprising:
  - a) an anisotropically etched groove in the substrate; and

b) a dry pit intersecting the groove at one end of the groove, wherein the dry pit comprises an apex that intersects a wedge area of the groove.

10. (Original) The substrate of claim 9 wherein the dry pit is formed before the groove.
11. (Original) The substrate of claim 9 wherein the dry pit covers a wedge area of the groove.
12. (Original) The substrate of claim 9 wherein the dry pit is deeper than the groove.
13. (Original) The substrate of claim 9 further comprising a wet pit disposed adjacent to the dry pit and opposite the groove.
14. (Original) The substrate of claim 9 wherein the crystalline substrate is a <100> silicon substrate.
15. (Currently Amended): A micromachined crystalline substrate comprising:
  - a) a first anisotropically etched groove in the substrate;
  - b) a second anisotropically etched groove in the substrate, parallel with the first groove; and
  - c) a dry pit disposed between the first groove and second groove, wherein the dry pit comprises an apex that intersects a wedge area of the first groove[[,]] and intersects a wedge area of the second groove.
16. (Original) The substrate of claim 15 wherein the dry pit is formed before the grooves.
17. (Original) The substrate of claim 15 wherein the dry pit covers a wedge area of each groove.
18. (Original) The substrate of claim 15 wherein the dry pit is deeper than the first groove and second groove.

19. (Original) The substrate of claim 15 wherein the first groove and second groove are in-line.
20. (Original) The substrate of claim 15 wherein the crystalline substrate is a <100> silicon substrate.
21. (Original) A micromachined crystalline substrate comprising:
- a) an anisotropically etched groove in the substrate; and
  - b) a dry pit intersecting the groove at one end of the groove, wherein the dry pit intersects the groove at an angles of 45 degree or less, so that a wedge is not present in the groove adjacent to the dry pit.
22. (Original) The substrate of claim 21 wherein the dry pit is formed before the groove.
23. (Original) The substrate of claim 21 wherein the dry pit is deeper than the groove.
24. (Original) The substrate of claim 21 wherein the crystalline substrate is a <100> silicon substrate.
25. (Original) A micromachined crystalline substrate comprising:
- a) a first anisotropically etched groove in the substrate;
  - b) a second anisotropically etched groove in the substrate, perpendicular with the first groove and joined with the first groove; and
  - c) a dry pit disposed at a convex corner location where the first and second grooves meet.
26. (Original) The substrate of claim 25 wherein the dry pit is formed before the grooves.
27. (Original) The substrate of claim 25 wherein the dry pit is deeper than the first groove and second groove.

28. (Original) The substrate of claim 25 wherein the dry pit covers a convex corner location defined by the first and second grooves.

29. (Original) The substrate of claim 25 wherein the crystalline substrate is a <100> silicon substrate.

30. (Original) A micromachined crystalline substrate comprising:

- a) an anisotropically etched wet pit in the substrate;
- b) a U-shaped dry pit intersecting the wet pit; and
- c) a U-area inside the U-shaped dry pit, wherein the U-shaped dry pit is disposed so that the U-area is not part of the wet pit.

31. (Original) The substrate of claim 30 wherein the dry pit is formed before the wet pit.

32. (Original) The substrate of claim 30 wherein the dry pit is deeper than the wet pit.

33. (Original) The substrate of claim 30 wherein the wet pit is deeper than the dry pit.

34. (Original) The substrate of claim 30 further comprising a laser disposed on the U-area, and a ball lens disposed in the wet pit.

35. (Original) The substrate of claim 30 wherein the crystalline substrate is a <100> silicon substrate.

36-48. (Canceled)

49. (New) The optical submount of claim 1 wherein the dry pit has a triangular cross-sectional shape within a plane parallel to the plane of the substrate.

50. (New) The substrate of claim 9 wherein the dry pit comprises a triangular shape.

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51. (New) The substrate of claim 9 wherein the dry pit has a triangular cross-sectional shape within a plane parallel to the plane of the substrate.

52. (New) The substrate of claim 9 wherein the dry pit has a diamond cross-sectional shape within a plane parallel to the plane of the substrate.

53. (New) The substrate of claim 15 wherein the dry pit comprises a triangular shape.

54. (New) The substrate of claim 15 wherein the dry pit has a triangular cross-sectional shape within a plane parallel to the plane of the substrate.

55. (New) The substrate of claim 15 wherein the dry pit has a diamond cross-sectional shape within a plane parallel to the plane of the substrate.